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(54) Title: HIGH BREAKDOWN VOLTAGE DIELECTRIC POLYMER FILMS, A METHOD OF PRODUCING THE SAME AND USES THEREOF

(57) Abstract: According to an example aspect of the present invention, there are provided dielectric polymer films comprising a gap-fill material forming composition, and uses of the dielectric polymer films in semiconductor devices, optical elements and optically active devices. The present invention also relates to methods of producing gap-fill material forming compositions and dielectric polymer films comprising said compositions.



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